



**Alfa-MOS  
Technology**

**AFN5808W  
20V N-Channel  
Enhancement Mode MOSFET**

## General Description

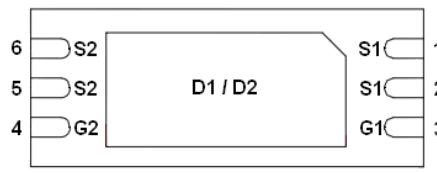
AFN5808W, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

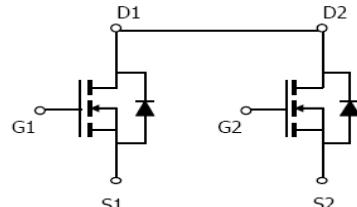
## Features

- $I_D=6.2A, R_{DS(ON)}=32m\Omega @ V_{GS}=4.5V$
- $I_D=4.6A, R_{DS(ON)}=38m\Omega @ V_{GS}=2.5V$
- $I_D=3.8A, R_{DS(ON)}=50m\Omega @ V_{GS}=1.8V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- DFN2X5-6L package design

## Pin Description ( DFN2X5-6L )



BOTTOM VIEW



TOP VIEW

## Application

- Load Switch
- Portable Equipment
- Battery Powered System

## Pin Define

Pin	Symbol	Description
1	S1	Source1
2	S1	Source1
3	G1	Gate1
4	G2	Gate2
5	S2	Source2
6	S2	Source2

## Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN5808WFN256RG	AFN5808W YYMMDD	DFN2X5-6L	Tape & Reel	2500 EA

※ YY year code

※ MM month code

※ DD date code

※ AFN5808WFN256RG : 7" Tape & Reel ; Pb- Free ; Halogen -Free



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### Absolute Maximum Ratings

( $T_A=25^\circ\text{C}$  Unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	20	V
Gate -Source Voltage	$V_{GSS}$	$\pm 12$	V
Continuous Drain Current( $T_J=150^\circ\text{C}$ )	$I_D$	6.2	A
		3.8	
Pulsed Drain Current	$I_{DM}$	40	A
Continuous Source Current(Diode Conduction)	$I_S$	1.6	A
Power Dissipation	$P_D$	1.6	W
		1.0	
Operating Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55/150	$^\circ\text{C}$
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	120	$^\circ\text{C}/\text{W}$

### Electrical Characteristics

( $T_A=25^\circ\text{C}$  Unless otherwise noted)

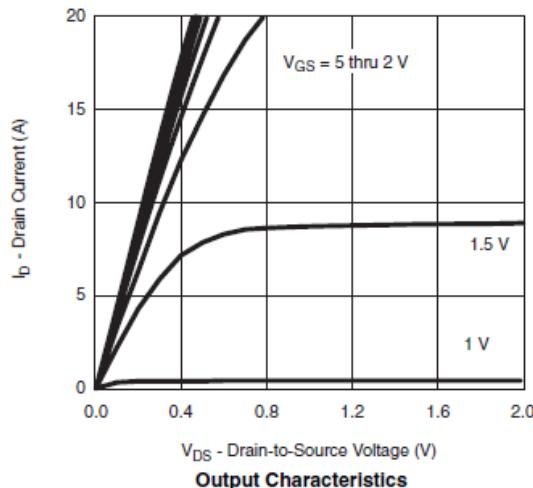
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	20			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.3		0.8	
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=16\text{V}, V_{GS}=0\text{V}$			1	uA
		$V_{DS}=16\text{V}, V_{GS}=0\text{V}$ $T_J=85^\circ\text{C}$			10	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \geq 5\text{V}, V_{GS}=4.5\text{V}$	6			A
		$V_{DS} \geq 5\text{V}, V_{GS}=2.5\text{V}$	4			
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=4.5\text{V}, I_D=6.2\text{A}$		26	32	m $\Omega$
		$V_{GS}=2.5\text{V}, I_D=4.6\text{A}$		31	38	
		$V_{GS}=1.8\text{V}, I_D=3.8\text{A}$		43	50	
Forward Transconductance	$g_{FS}$	$V_{DS}=5\text{V}, I_D=3.6\text{A}$		10		S
Diode Forward Voltage	$V_{SD}$	$I_S=1.6\text{A}, V_{GS}=0\text{V}$		0.85	1.2	V
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS}=10\text{V}, V_{GS}=4.5\text{V}$ $I_D=6.2\text{A}$		6.2	10	nC
Gate-Source Charge	$Q_{gs}$			1.0		
Gate-Drain Charge	$Q_{gd}$			1.6		
Input Capacitance	$C_{iss}$	$V_{DS}=10\text{V}, V_{GS}=0\text{V}$ $f=1\text{MHz}$		480		pF
Output Capacitance	$C_{oss}$			160		
Reverse Transfer Capacitance	$C_{rss}$			100		
Turn-On Time	$t_{d(on)}$	$V_{DD}=10\text{V}, R_L=1.9\Omega$ $I_D=5.4\text{A}, V_{GEN}=4.5\text{V}$ $R_G=1\Omega$		10	16	ns
	$t_r$			12	25	
Turn-Off Time	$t_{d(off)}$			25	40	
	$t_f$			12	20	



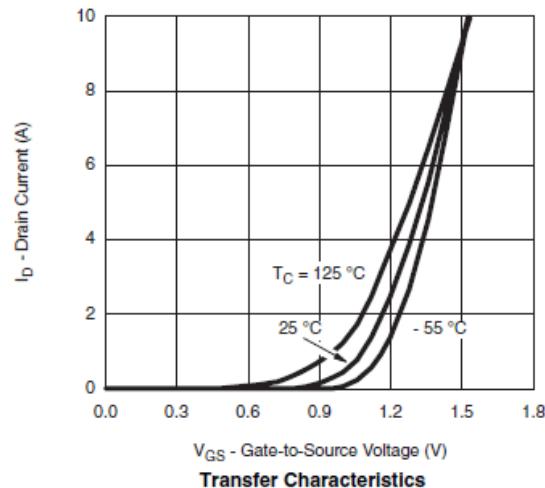
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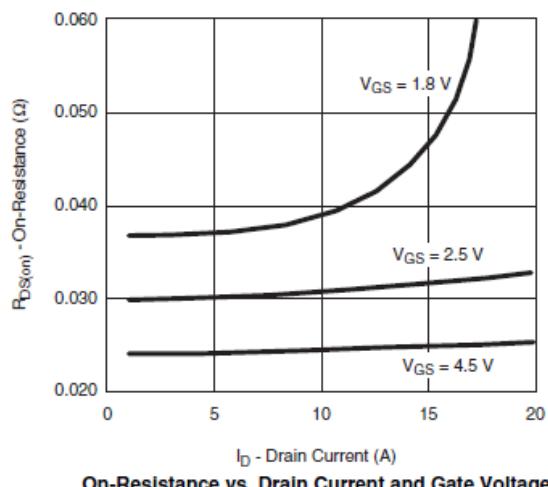
### Typical Characteristics



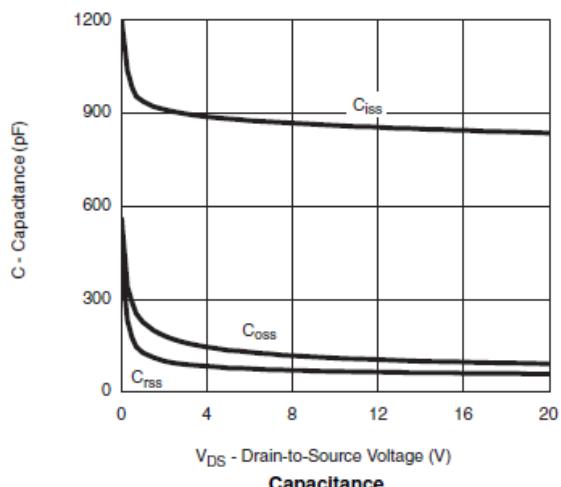
**Output Characteristics**



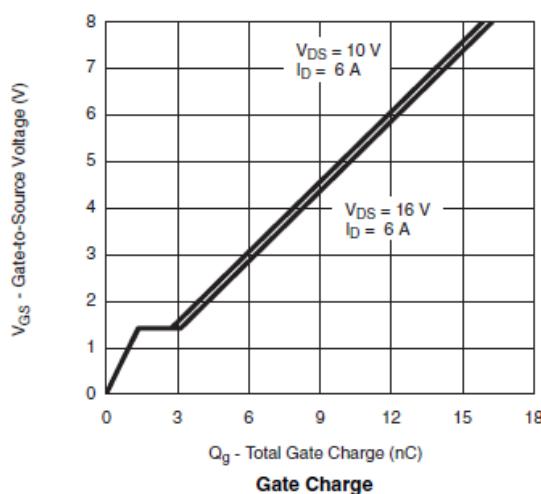
**Transfer Characteristics**



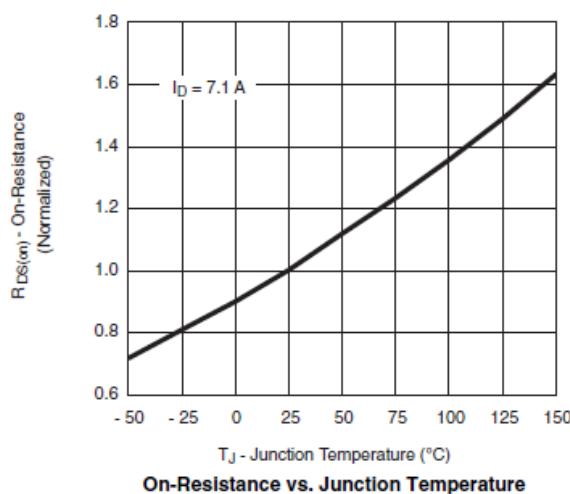
**On-Resistance vs. Drain Current and Gate Voltage**



**Capacitance**



**Gate Charge**



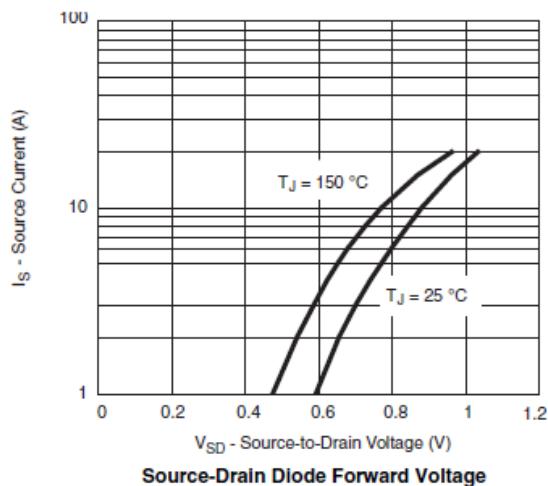
**On-Resistance vs. Junction Temperature**



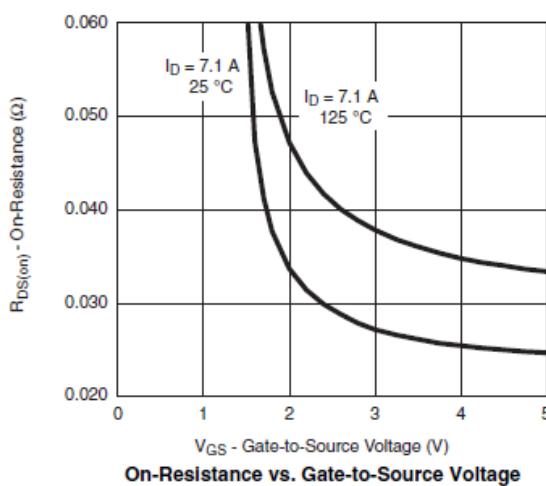
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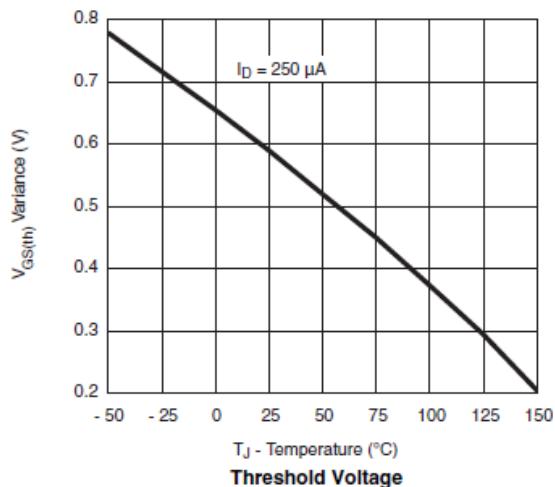
### Typical Characteristics



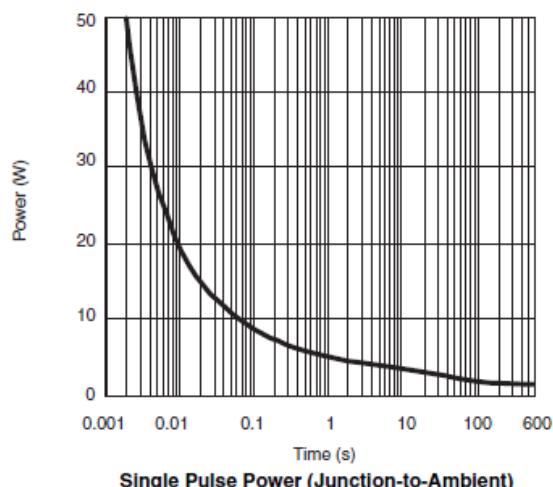
Source-Drain Diode Forward Voltage



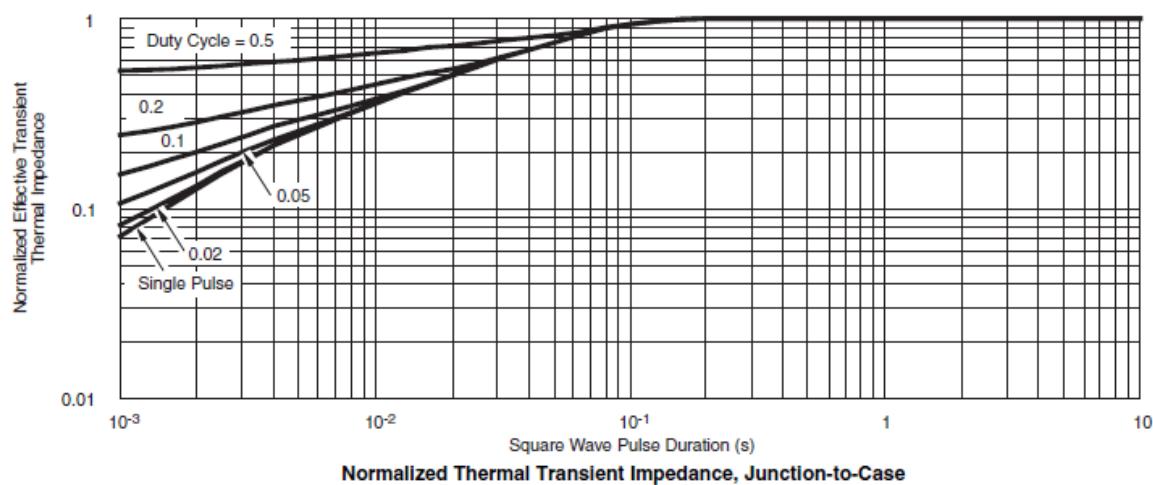
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power (Junction-to-Ambient)



Normalized Thermal Transient Impedance, Junction-to-Case

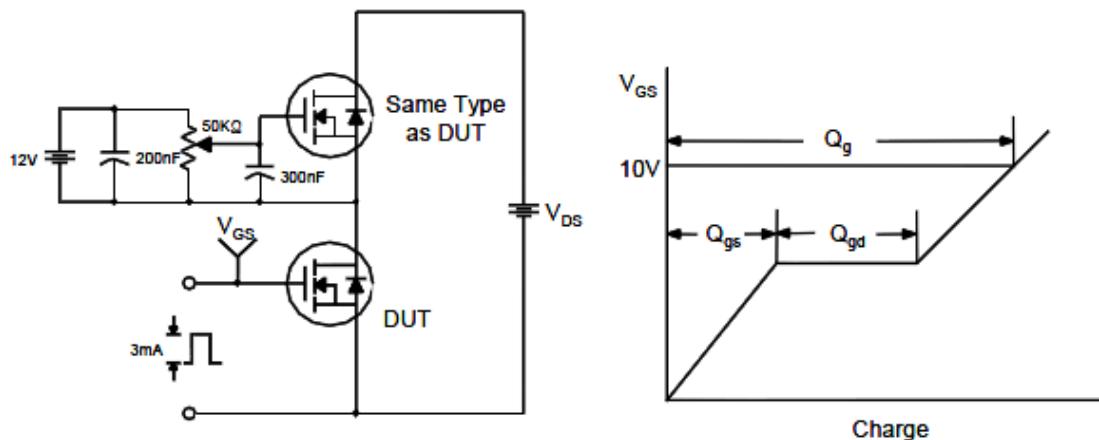


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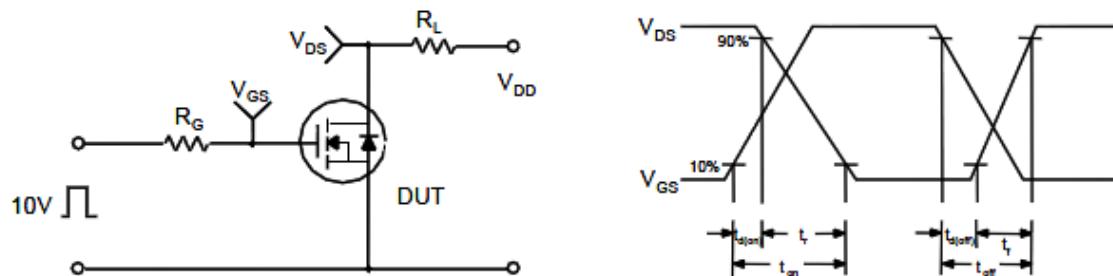
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## Typical Characteristics

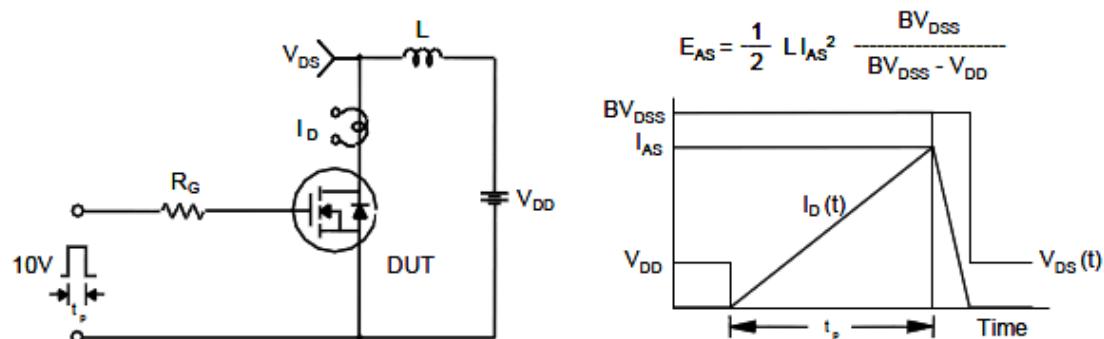
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

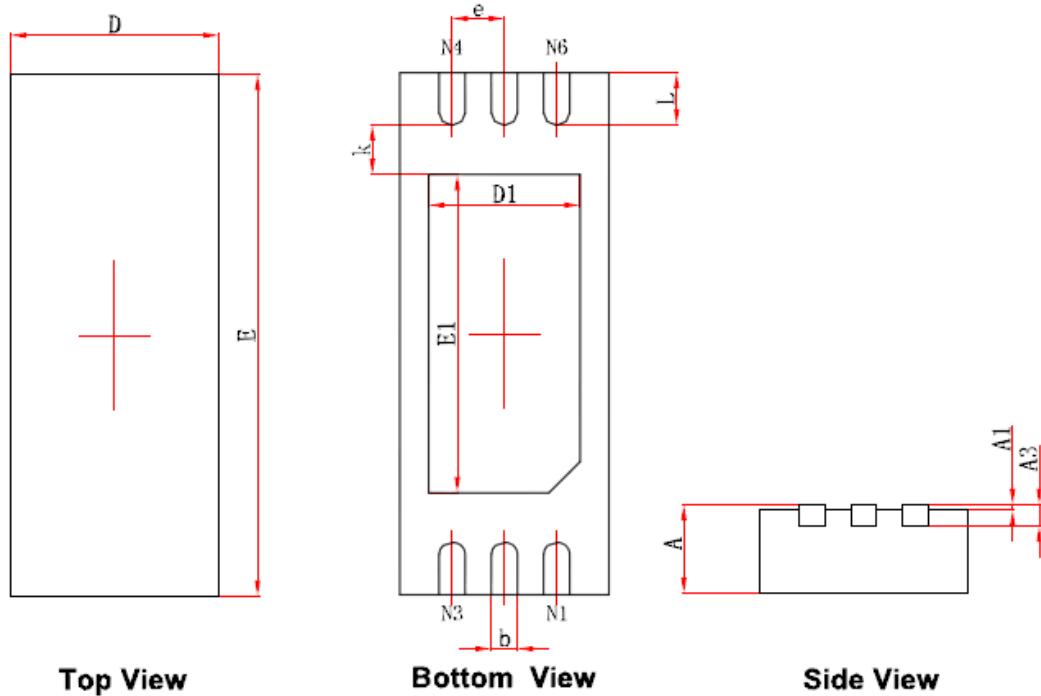




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**Package Information ( DFN2X5-6L )**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.924	2.076	0.076	0.082
E	4.924	5.076	0.194	0.200
D1	1.350	1.550	0.053	0.061
E1	2.950	3.150	0.116	0.124
k	0.200MIN.		0.008MIN.	
b	0.200	0.300	0.008	0.012
e	0.500TYP.		0.020TYP.	
L	0.424	0.576	0.017	0.023

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